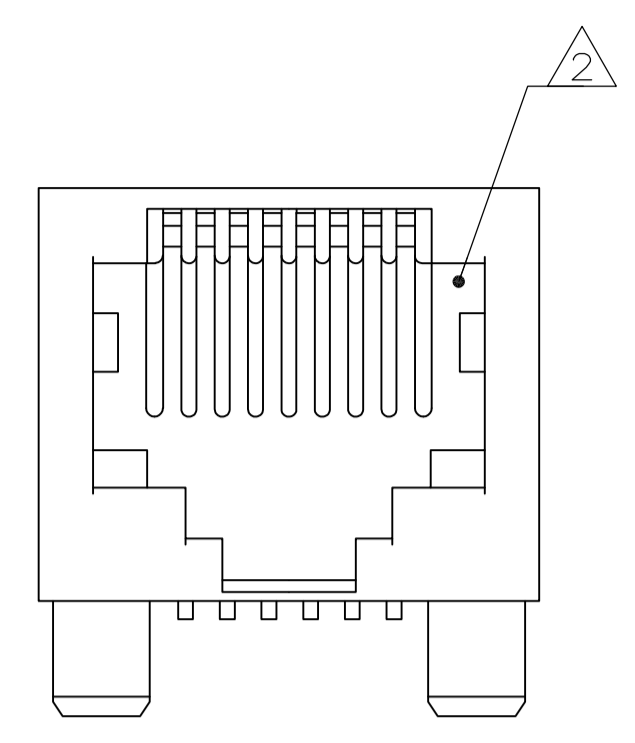
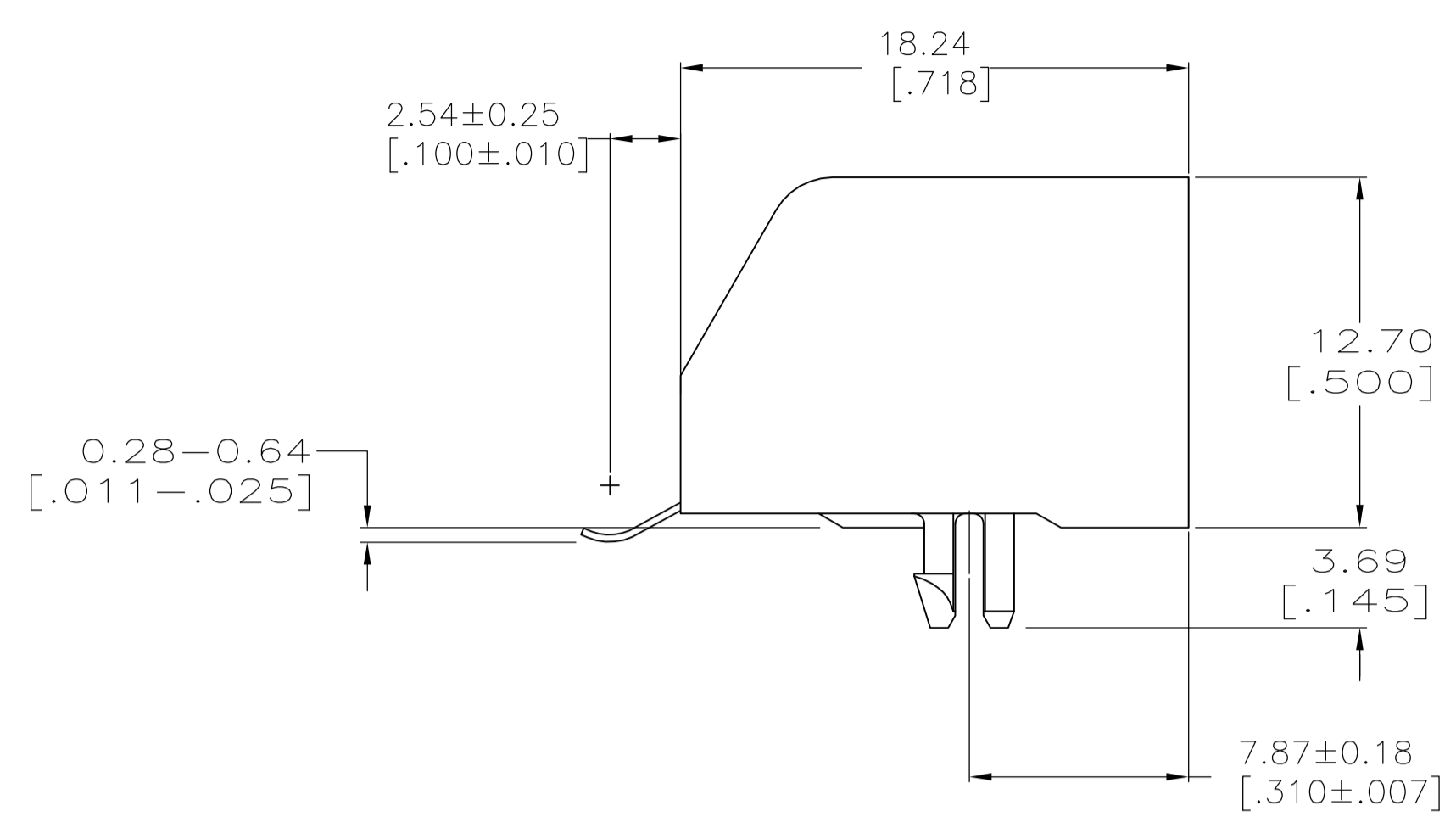
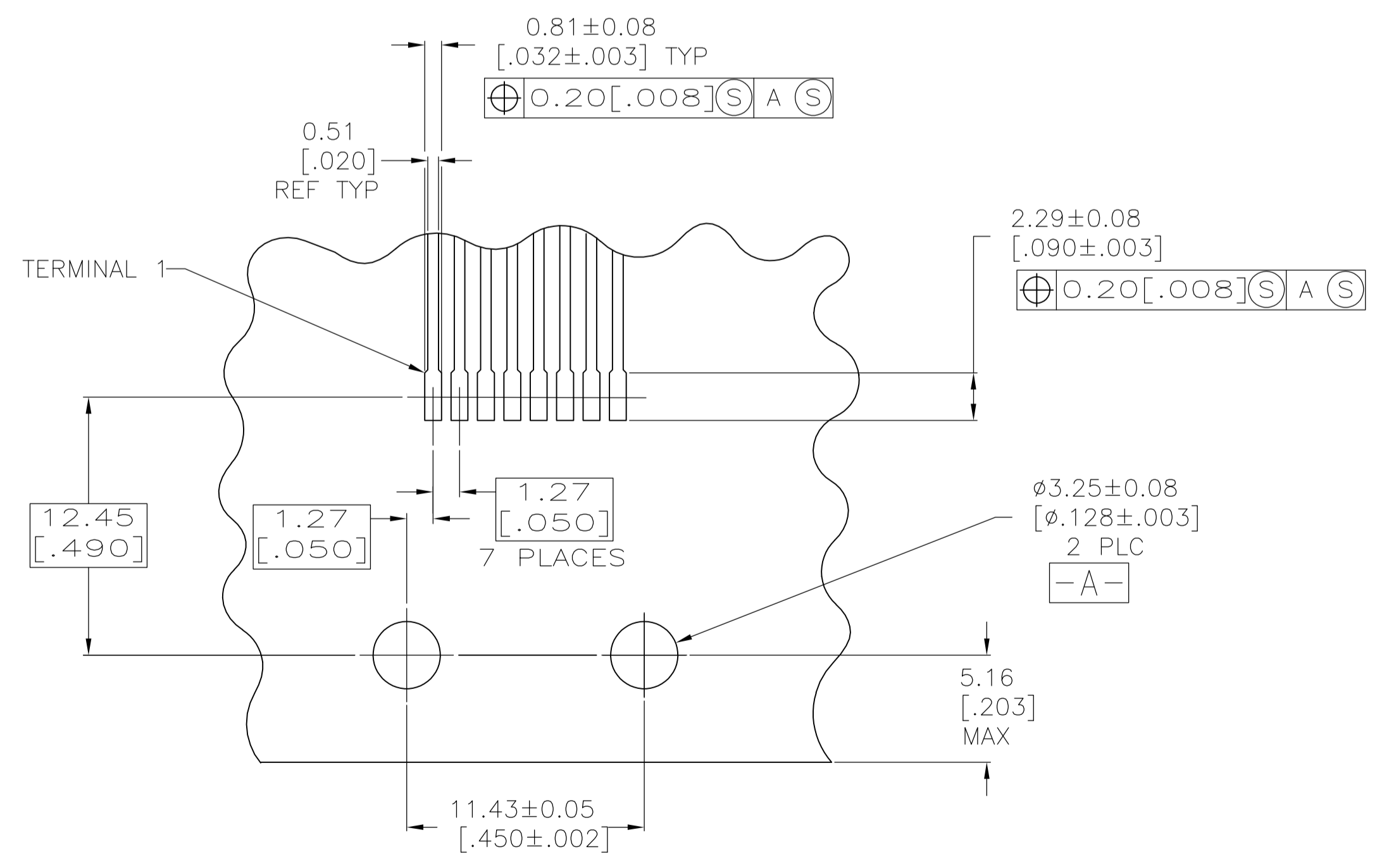
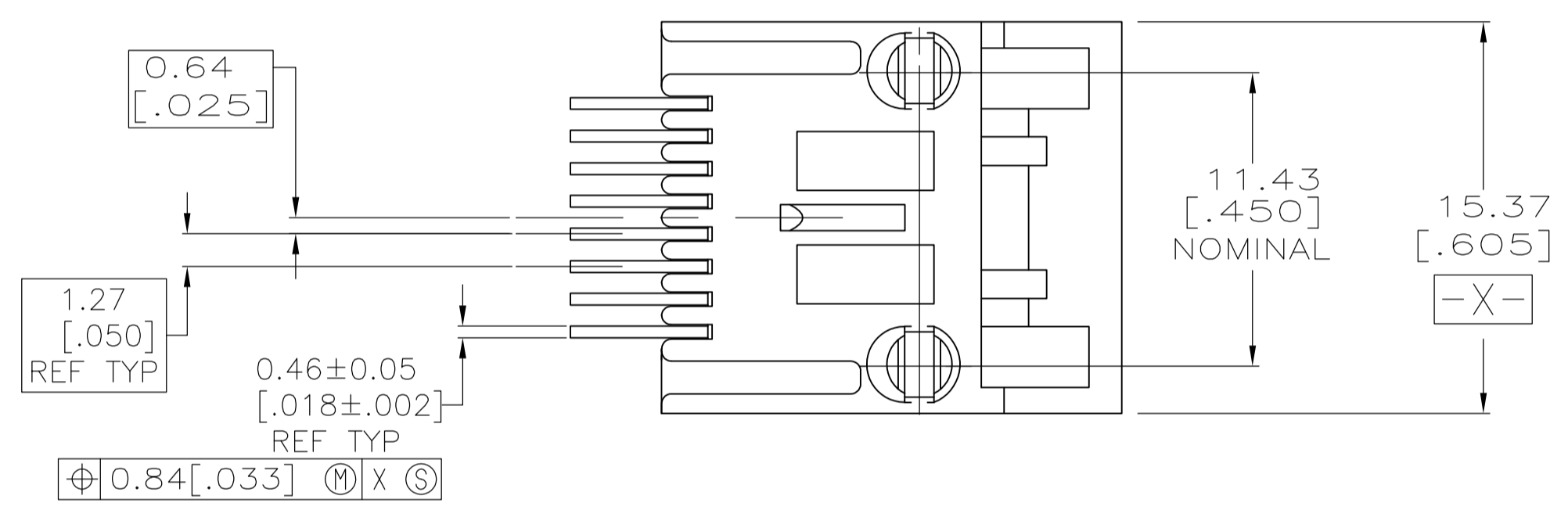


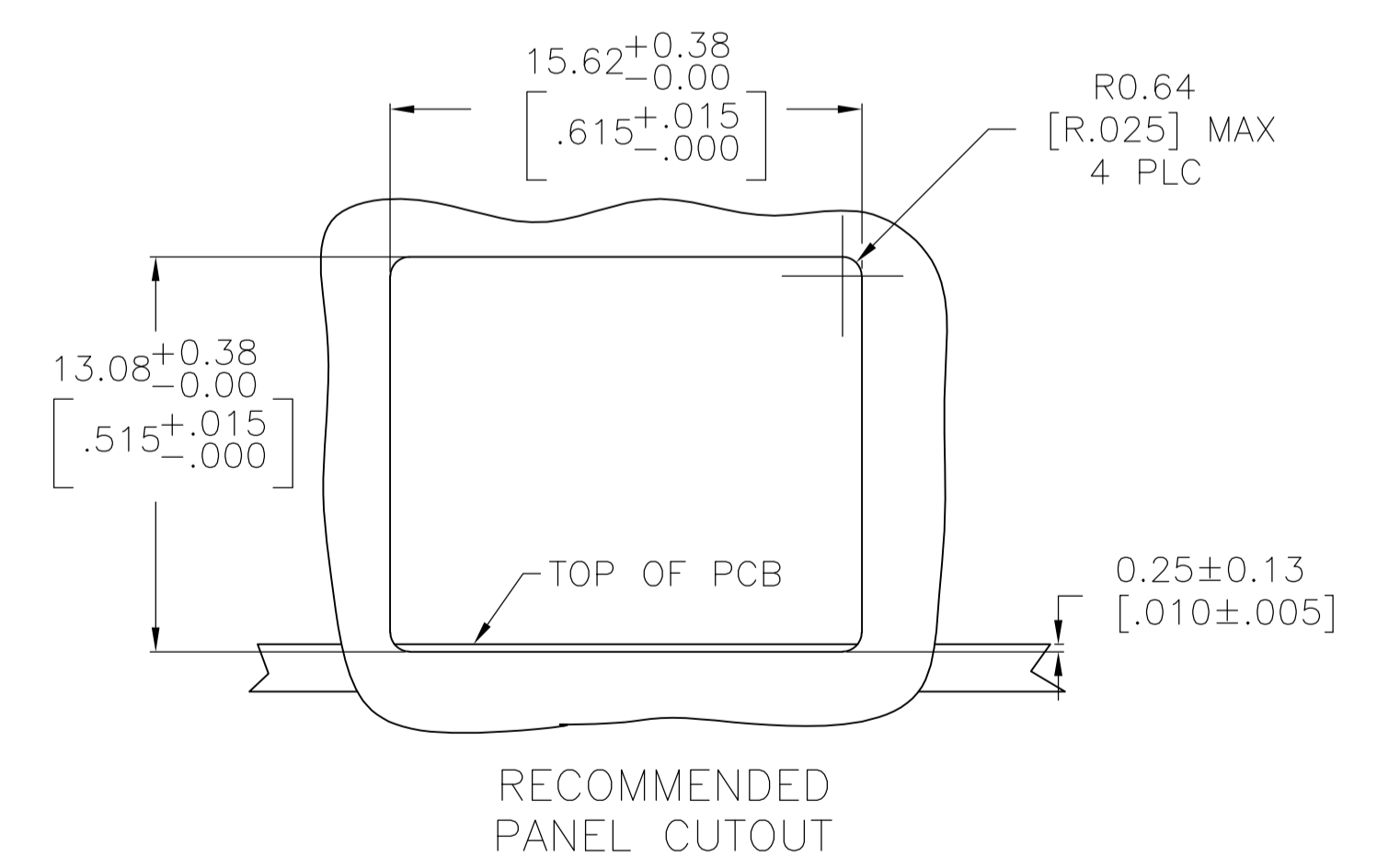
LOC		DIST		REVISIONS			
P	LTR	DESCRIPTION	DATE	DWN	APVD		
B		ECO-07-019669	27AUG2007	LAM	PR		



- MATERIAL: HOUSING - HTN MOLDING COMPOUND, 94 VO, COLOR: BLACK.
 TERMINAL - 0.36 [.014] THICK PHOS-BRONZE PLATE WITH 1.27μm [.000050] MINIMUM THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81μm [.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27μm [.000050] MINIMUM THICK NICKEL UNDERPLATE.
 - CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68, SUBPART F.
 - ALL DIMENSIONS SHOWN ARE MAXIMUM UNLESS OTHERWISE SPECIFIED AND ARE PRIOR TO SURFACE MOUNT PROCESSING.
 - SNAP-IN RETENTION FEATURE ACCOMMODATES 1.45-1.70 [.062±.005] THICK PRINTED CIRCUIT BOARD.
- ASSEMBLIES ARE PACKAGED 36 IN A TUBE.
- ASSEMBLIES ARE BULK PACKAGED.



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT
 COMPONENT SIDE



5	5555764-3
6	5555764-1
PACKAGED	PART NO

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN G. ATTADIA - DOCKS 08/JUN/2005		Tyco Electronics Corporation	
DIMENSIONS: mm [INCHES]		TOLERANCES UNLESS OTHERWISE SPECIFIED:		Tyco Electronics Corporation Harrisburg, PA 17105-3608	
0 PLC ± -		1 PLC ± -		APVD S. FLICKINGER 08/JUN/2005	
1 PLC ± -		2 PLC ± -		NAME MODULAR JACK ASSEMBLY, 8 POSITION, LOW PROFILE, RIGHT ANGLE, SURFACE MOUNT	
2 PLC ± -		3 PLC ± -		PRODUCT SPEC 108-1163	
3 PLC ± -		4 PLC ± -		APPLICATION SPEC 114-6040	
4 PLC ± -		ANGLES ± -		SIZE CAGE CODE DRAWING NO RESTRICTED TO	
MATERIAL SEE NOTE 1		FINISH SEE NOTE 1		A1 00779 5555764	
		WEIGHT -		CUSTOMER DRAWING SCALE 4:1 SHEET 1 OF 1 REV B	